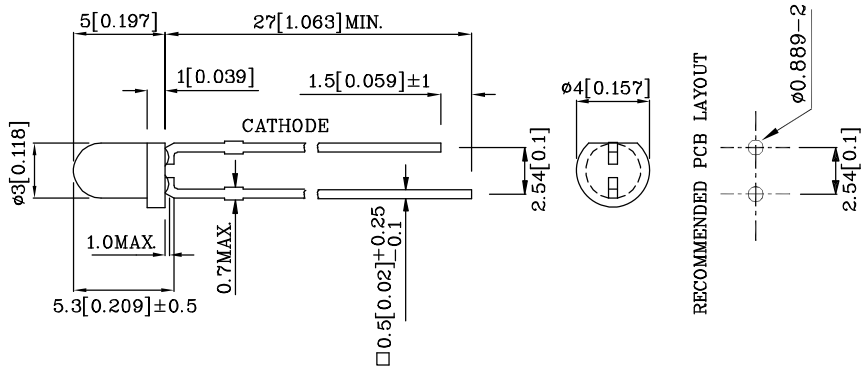
Part Number: XBMR34D

T-1 (3mm) BLINKING LED LAMP

Features

- 3mm package with built-in blinking IC
- Blinking frequency range: 3.0Hz to 1.5Hz
- Operation voltage range: 3.5V to 14V
- RoHS compliant

Package Schematics



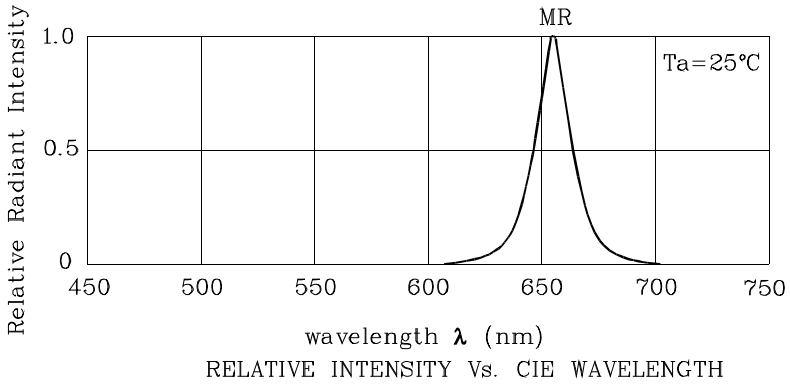
Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T_A=25°C)		**MR (GaAlAs)**	**Unit**
Reverse Voltage	V_R	0.5	V
Forward Voltage	V_F	14	V
Power Dissipation	P_D	310	mW
Operating Temperature	T_A	-40 ~ +70	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

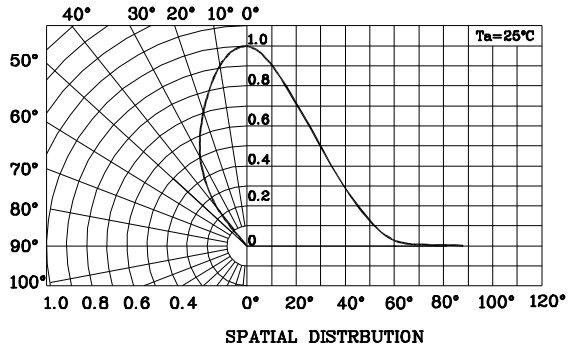
Operating Characteristics (T_A=25°C)		**MR (GaAlAs)**	**Unit**
Forward Current (Min.) (V_F=3.5V)	I_F	8	mA
Forward Current (Typ.) (V_F=5V)	I_F	22	mA
Supply Current (Typ.) (V_F=3.5V)	I_{SON}	8	mA
Supply Current (Typ.) (V_F=14V)	I_{SON}	44	mA
Blink Frequency (Min.~Max.) (V_F=3.5V~14V)	f	1.5~3	Hz
Wavelength of Peak Emission CIE127-2007* (Typ.)	λP	655*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.)	λD	640*	nm
Spectral Line Full Width At Half-Maximum (Typ.)	△λ	20	nm

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (V_F=9V) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 2θ 1/2
				min.	typ.		
XBMR34D	Red	GaAlAs	Red Diffused	120 40*	317 98*	655*	60°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

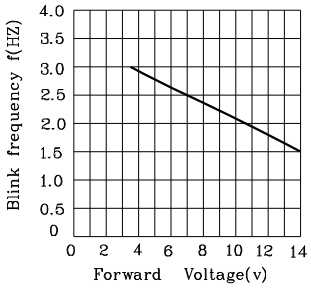


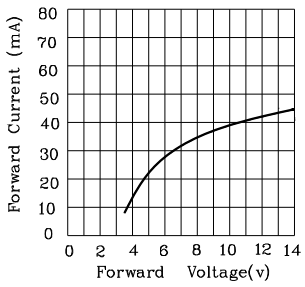
RELATIVE INTENSITY Vs. CIE WAVELENGTH



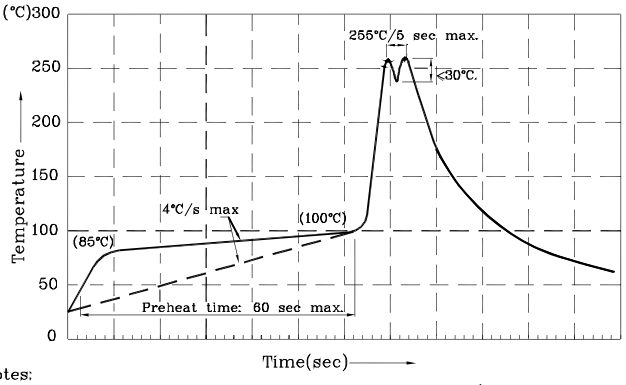
SPATIAL DISTRBUTION

❖ **MR**



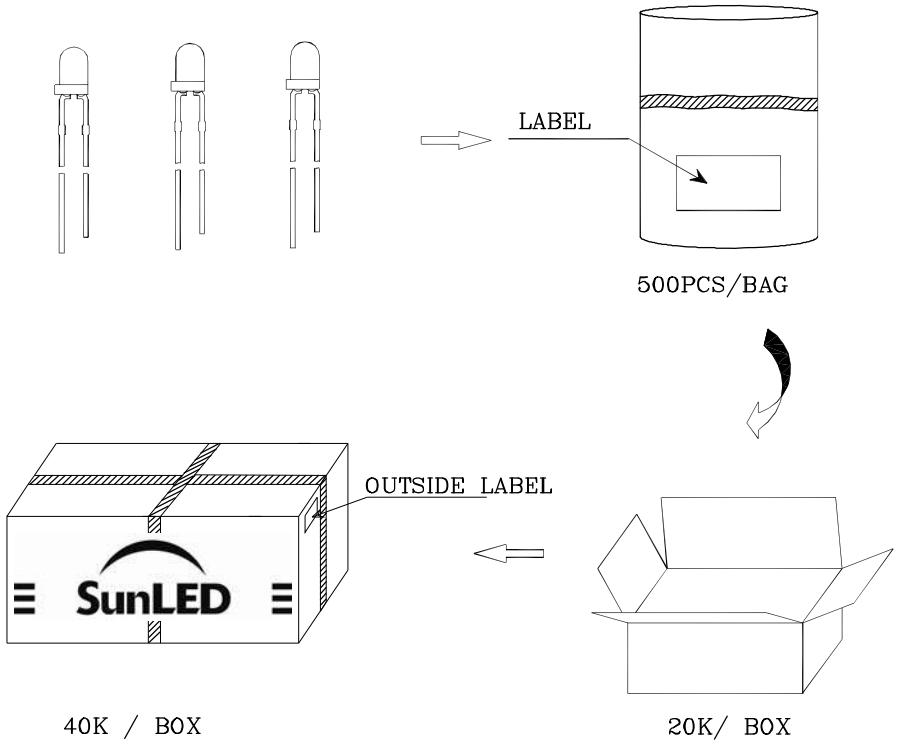


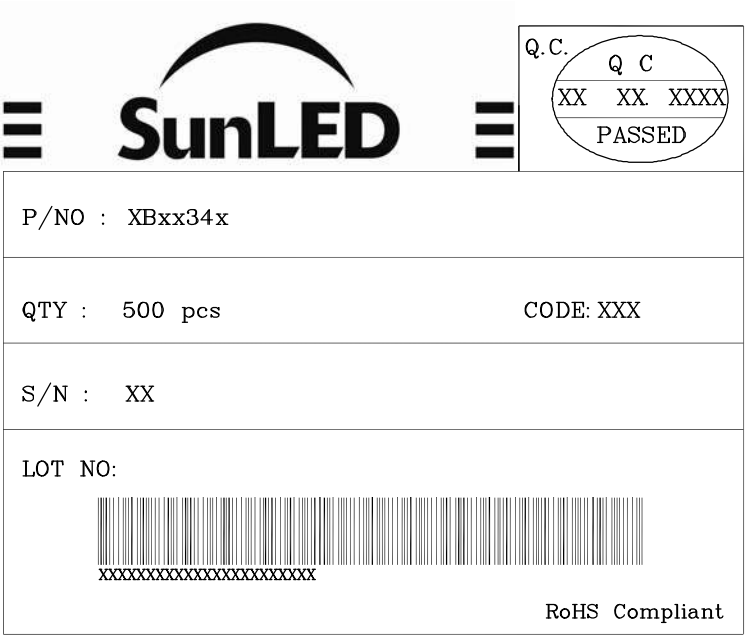
Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:
1. Recommend pre-heat temperature of 105℃ or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260℃
2. Peak wave soldering temperature between 245℃ ~ 255℃ for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85℃.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

PACKING & LABEL SPECIFICATIONS





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